

ABSTRACT OF THE DISCLOSURE

A process for machining a wafer-like workpiece between two plates, in which material is abraded from the workpiece under the influence of an auxiliary substance supplied and of ~~28.05.03 Hz~~ ^{28.05.03 Hz} ~~pressure 28.05.03 Dm~~ ^{pressure 28.05.03 Dm} ~~pressure~~ ^{28.05.03 Dm} ~~weight~~ ^{28.05.03 Hz} acting on the workpiece. In this process, the ~~load~~ ^{28.05.03 Dm} ~~from the weight~~ ^{28.05.03 Hz} on the workpiece is significantly reduced and then increased again at least once during the machining of the workpiece, and the supply of the auxiliary substance is ~~28.05.03 Dm~~ ^{28.05.03 Dm} ~~pressure~~ ^{28.05.03 Hz} reduced as the ~~weight~~ ^{28.05.03 Hz} is increased.